

J10730

PATENT NUMBER and
ISSUE DATE

U.S. UTILITY Patent Application

APPL NUM 10050166	FILING DATE 01/18/2002	CLASS 438	SUBCLASS 157	GAU 2812	EXAMINER Danech
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****APPLICANTS:** Horibe Hiroshi

****CONTINUING DATA VERIFIED:**

**** FOREIGN APPLICATIONS VERIFIED:**
JAPAN 2001-256892 09/27/2001

PG PUB DO NOT PUBLISH ☐ RESCIND ☐

Foreign priority claimed ☐ yes ☐ no
35 USC 119 conditions met ☐ yes ☐ no
Verified and Acknowledged Examiners's initials

ATTORNEY DOCKET NO
50090-466

TITLE : Semiconductor device and wire bonding apparatus

U.S. DEPT. OF COMM./PAT & TM-PTO-433L(R)w 12-94

NOTICE OF ALLOWANCE MAILED		Assistant Examiner	CLAIMS ALLOWED	
			Total Claims	Print Claim for O.G.
ISSUE FEE		Primary Examiner	DRAWING	
Amount Due	Date Paid		Sheets Drwg.	Figs. Drwg.
<input type="checkbox"/> TERMINAL		PREPARED FOR ISSUE	Application Examiner	
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